

Serial No. 10/082,392

IN THE TITLE:

The title has been amended herein. Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date), please enter the title as amended.

**METHODS FOR FABRICATING  
DUAL LOC SEMICONDUCTOR DIE ASSEMBLY EMPLOYING  
FLOATING LEAD FINGER STRUCTURE**

**Match and Return**

**IN THE SPECIFICATION:**

Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date) please enter the substitute specification in clean form and including paragraph numbers [0001] through [0041] and Abstract attached hereto as Appendix A. A marked-up substitute specification to clearly identify amendments to the specification as required by 37 C.F.R. § 1.121(b)(3)(iii) is attached hereto as Appendix B. It is respectfully submitted that the substitute specification does not introduce new matter into the above-referenced patent application.